



SNS COLLEGE OF TECHNOLOGY

Coimbatore-35 An Autonomous Institution

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DEPARTMENT OF FOOD TECHNOLOGY

19FTT201 – HEAT AND MASS TRANSFER UNIT 1 - CONDUCTION II YEAR IV SEM

Topic 5 1D SS Conduction equation for wall





Conduction heat transfer: Objectives of conduction analysis: is Primary objective is to determine the temperature field Ta) na body (ie has temperature varies with position within the body]. er T(x) depends on boundary condition, initial condition, material properties (P, K, Cp), and geometry. it why we need temperature T(x). as Compute heat flux at any point (ung Fame by compute thermal strenes, expansion, deflection due to temp etc, of Darign products in applications such as. mulation thickness, chip temperature calculations (electronics), Heat treatment at wetale. Boundary and Initial condition: is Heat equation is second order in spatial coordinate. Hence, 285 needed for each coordinate. * ID problem: 28C M X-directron. extend equation is first order in time. Hence





one-dimensional steady state heat conduction without heat generation: q"=0, 25=0. $\frac{\partial}{\partial r}\left(k,\frac{\partial T}{\partial r}\right)=0, \rightarrow k, \frac{d^{2}T}{\partial r^{2}}=0, \longrightarrow 0$ dT =0. Integrating the equation once. Ti $\frac{dT}{dt} = C_1 \rightarrow \textcircled{2} \qquad \xrightarrow{Q_1}$ Integrating the equation again. $T = C_1 x + C_2 \longrightarrow \textcircled{3}$ To determine the constants C, & C2, appling the boundary anditions: ie @ x=0, T=T, \rightarrow T, = C, 0+C2 \rightarrow C2=T, \rightarrow () $k \in \mathbb{X} = L, T = T_2 = T_2 = C_1 L + C_2$ T2=GL+T, ~: C2=T, . G=(T2-T1)→3 L. TW. : 3 becomes, $T = (T_2 - T_1) \times + T_1 \rightarrow T_1 - T_1 = \frac{1}{L} \rightarrow 0$ Temperature distribution across the place wall.

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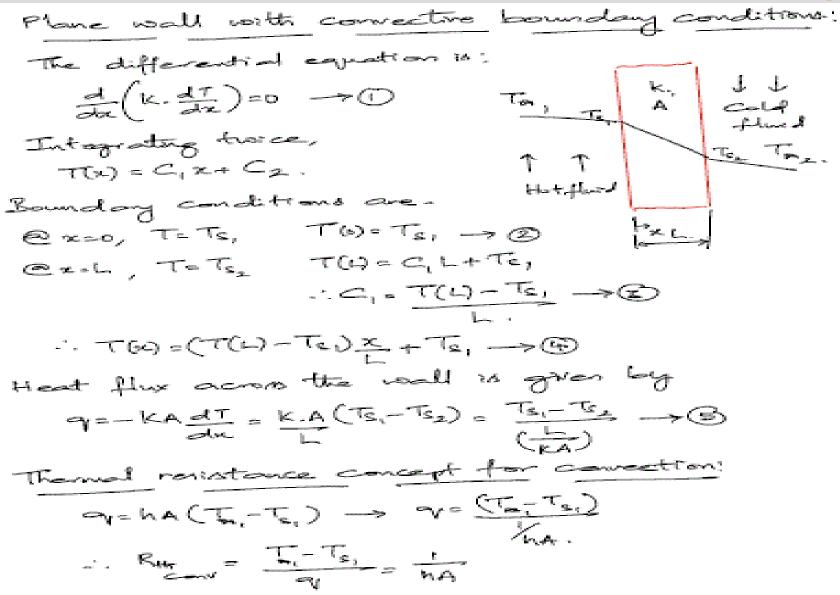


Rate of heat transfer through the plane wall: Q=-KA.dT -> @ [From anduction construe] $Q = -K A \frac{T_2 - T_1}{L}$ $r_1 = C_1 = \frac{T_2 - T_1}{L}$ $Q = k. A_{k} \underbrace{(T_{i} - T_{e})}_{L} \rightarrow a T_{e} \underbrace{(T_{i} - T_{e})}_{L} a T_{e} \underbrace{(T_{i} - T_{$ Thermal resistance concept wing this law: $V = I, R, \rightarrow I = \frac{V}{R} \rightarrow \textcircled{O}, \quad V, \overrightarrow{purissure} V_{e}.$ Comparing equations @ and @, we have. Q=I; (Ti-Te)=V and LaneR. ... Themal resistance for the plane wall. $R_{th} = \frac{L}{KA} \rightarrow \textcircled{0} \qquad \fbox{M} = \frac{M^2 \cdot K}{W \cdot M^2} = \frac{K}{W}$ Thermal resistance circuit for plane wall. To the Te unit to 00 °C/w. Thermal resistance for convection from nexted las of cooling Q=hA(TE-Tm) -> Q=(TE-Tm) - RATE - hAs

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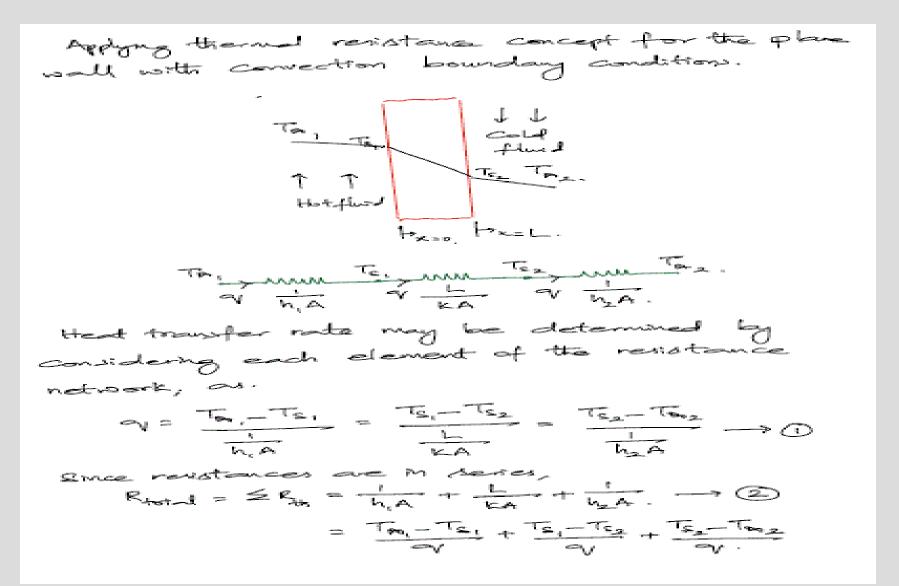




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1) Heat transfer deals with the rate of

- a. work transfer
- **b.** temperature transfer
- c. energy transfer
- **d.** none of the above

Answer : c. energy transfer





MCQ

2. The amount of heat required to raise the temperature of a substance by 1°C is called:

- A. work capacity
- B. heat capacity
- C. Energy capacity
- D. none of the above

Ans: B







- 3 Heat bring change
- A. Physical
- B. chemical
- C. reversible
- D. periodic

Ans: B Heat bring chemical change







4. The process of transfer of heat in liquids & gases is called:

- A. Conduction
- **B.** Radiation
- C. Convection
- D. Absorption

Ans: C It is the process of transfer of heat in liquids & gases



MCQ



5) Solids are not heated by convection because:

- A. solid are not free to move from one place to another
- B. molecules only vibrate about a fixed position
- C. both A and B
- D. none of the above

Ans: C Solids are not heated by convection because the molecules of a solid are not free to move from one place to another; they can only vibrate about a fixed position







Book references:

- Frank P. Incropera and David P. DeWitt, "Fundamentals of Heat and Mass Transfer", John Wiley and Sons, New Jersey, 6th Edition 1998 (Unit III, IV, V)
- Ozisik M.N, "Heat Transfer", McGraw-Hill Book Co., New Delhi, 3th Edition 1994(Unit I, II, III).
- Sachdeva R C, "Fundamentals of Engineering Heat and Mass Transfer" New Age International, New Delhi, 4th Edition 2010(Unit I, II, III).

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- <u>https:/12/12nptel.ac.in/12courses/12112/12101/12112101097/12</u>
- <u>https:/12/12nptel.ac.in/12courses/12112/12108/12112108149/12</u>
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